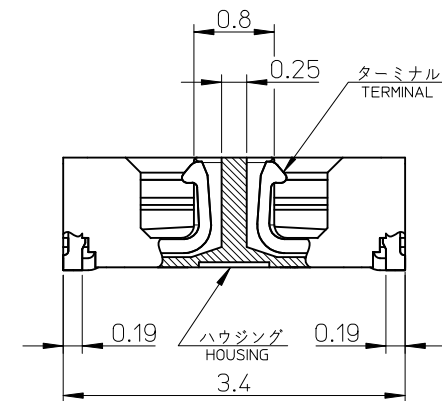
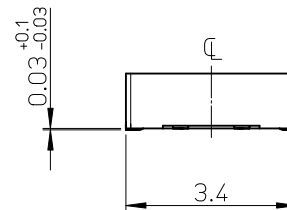
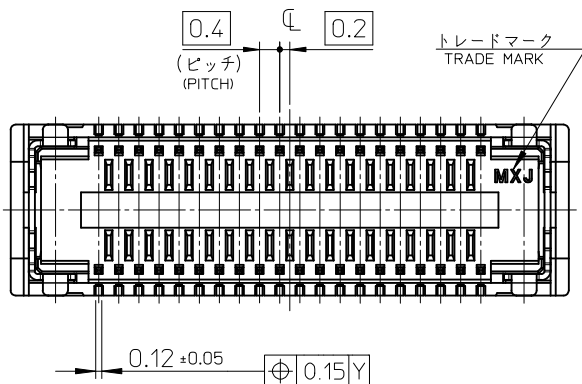
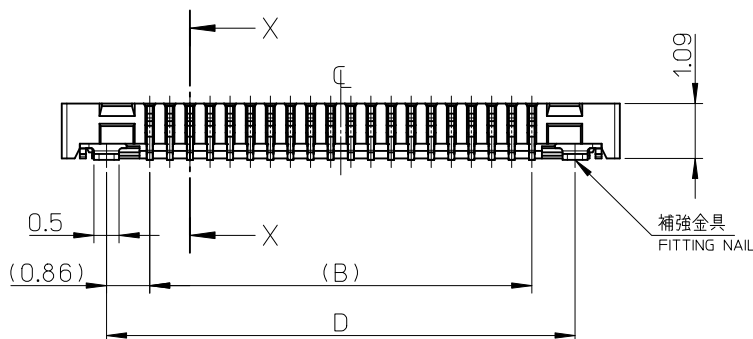
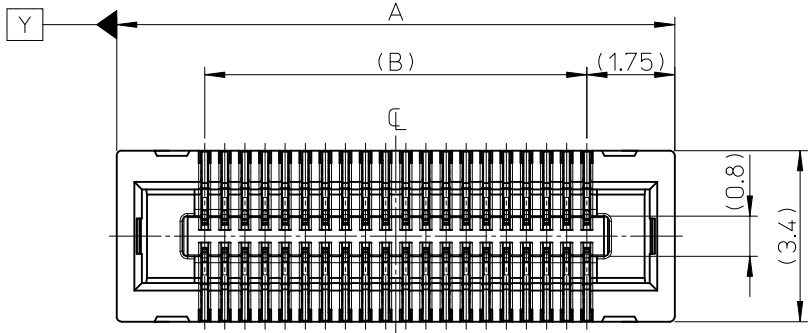


10 9 8 7 6 5 4 3 2 1

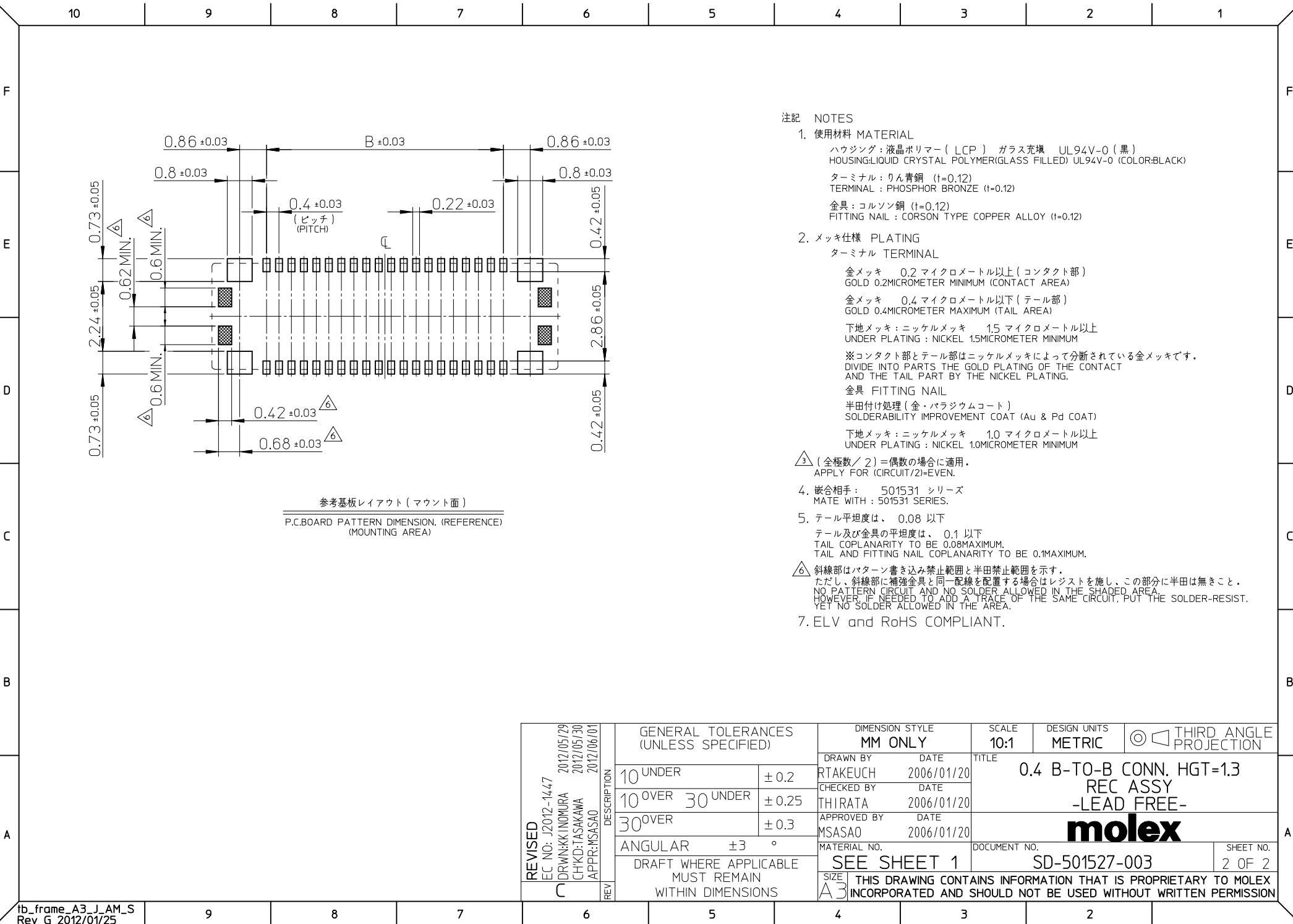


SECTION X-X

9.32	7.6	11.1	501527-0419	40
8.12	6.4	9.9	501527-3419	34
D	B	A	MATERIAL No.	CKT.
			MODEL No. : 501527-**19	

REVISED EC NO: J2012-1447 DRAWN BY: DRWKKI INOMURA 2012/05/29 CHKD: TASAKAWA 2012/05/30 APPR: MSASAO 2012/06/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION						
		10 UNDER	± 0.2	DRAWN BY RTAKEUCH	DATE 2006/01/20	TITLE 0.4 B-TO-B CONN. HGT=1.3 REC ASSY -LEAD FREE-								
		10 OVER 30 UNDER	± 0.25	CHECKED BY THIRATA	DATE 2006/01/20									
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2006/01/20	molex								
		ANGULAR ±3 °		MATERIAL NO. SEE CHART							DOCUMENT NO. SD-501527-003			SHEET NO. 1 OF 2
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										
	REV													

9 8 7 6 5 4 3 2



注記 NOTES

1. 使用材料 MATERIAL

ハウジング：液晶ポリマー（LCP）ガラス充填 UL94V-0（黒）
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0 (COLOR: BLACK)

ターミナル：りん青銅（t=0.12）
TERMINAL：PHOSPHOR BRONZE（t=0.12）

金具：コルソン銅（t=0.12）
FITTING NAIL：CORSON TYPE COPPER ALLOY（t=0.12）

2. メッキ仕様 PLATING

ターミナル TERMINAL

金メッキ 0.2 マイクロメートル以上（コンタクト部）
GOLD 0.2 MICROMETER MINIMUM (CONTACT AREA)

金メッキ 0.4 マイクロメートル以下（テール部）
GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)

下地メッキ：ニッケルメッキ 1.5 マイクロメートル以上
UNDER PLATING：NICKEL 1.5 MICROMETER MINIMUM

※コンタクト部とテール部はニッケルメッキによって分断されている金メッキです。
DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.

金具 FITTING NAIL

半田付け処理（金・パラジウムコート）
SOLDERABILITY IMPROVEMENT COAT (Au & Pd COAT)

下地メッキ：ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING：NICKEL 1.0 MICROMETER MINIMUM

- ③（全極数 / 2）= 偶数の場合に適用。
APPLY FOR (CIRCUIT/2)=EVEN.
4. 嵌合相手： 501531 シリーズ
MATE WITH：501531 SERIES.
5. テール平坦度は、0.08 以下
テール及び金具の平坦度は、0.1 以下
TAIL COPLANARITY TO BE 0.08 MAXIMUM.
TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM.
- ⑥ 斜線部はパターン書き込み禁止範囲と半田禁止範囲を示す。
ただし、斜線部に補強金具と同一配線を配置する場合はレジストを施し、この部分に半田は無きこと。
NO PATTERN CIRCUIT AND NO SOLDER ALLOWED IN THE SHADED AREA.
HOWEVER, IF NEEDED TO ADD A TRACE OF THE SAME CIRCUIT, PUT THE SOLDER-RESIST.
YET NO SOLDER ALLOWED IN THE AREA.
7. ELV and RoHS COMPLIANT.

REVISED EC NO.: J2012-1447 DRAWN: K KINURA CHKD: T ASAKAWA APPR: MSASAO	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY RTAKEUCH	DATE 2006/01/20	TITLE 0.4 B-TO-B CONN. HGT=1.3 REC ASSY -LEAD FREE- molex				
		10 OVER 30 UNDER	± 0.25	CHECKED BY THIRATA	DATE 2006/01/20					
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2006/01/20					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-501527-003		2 OF 2		
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

- D

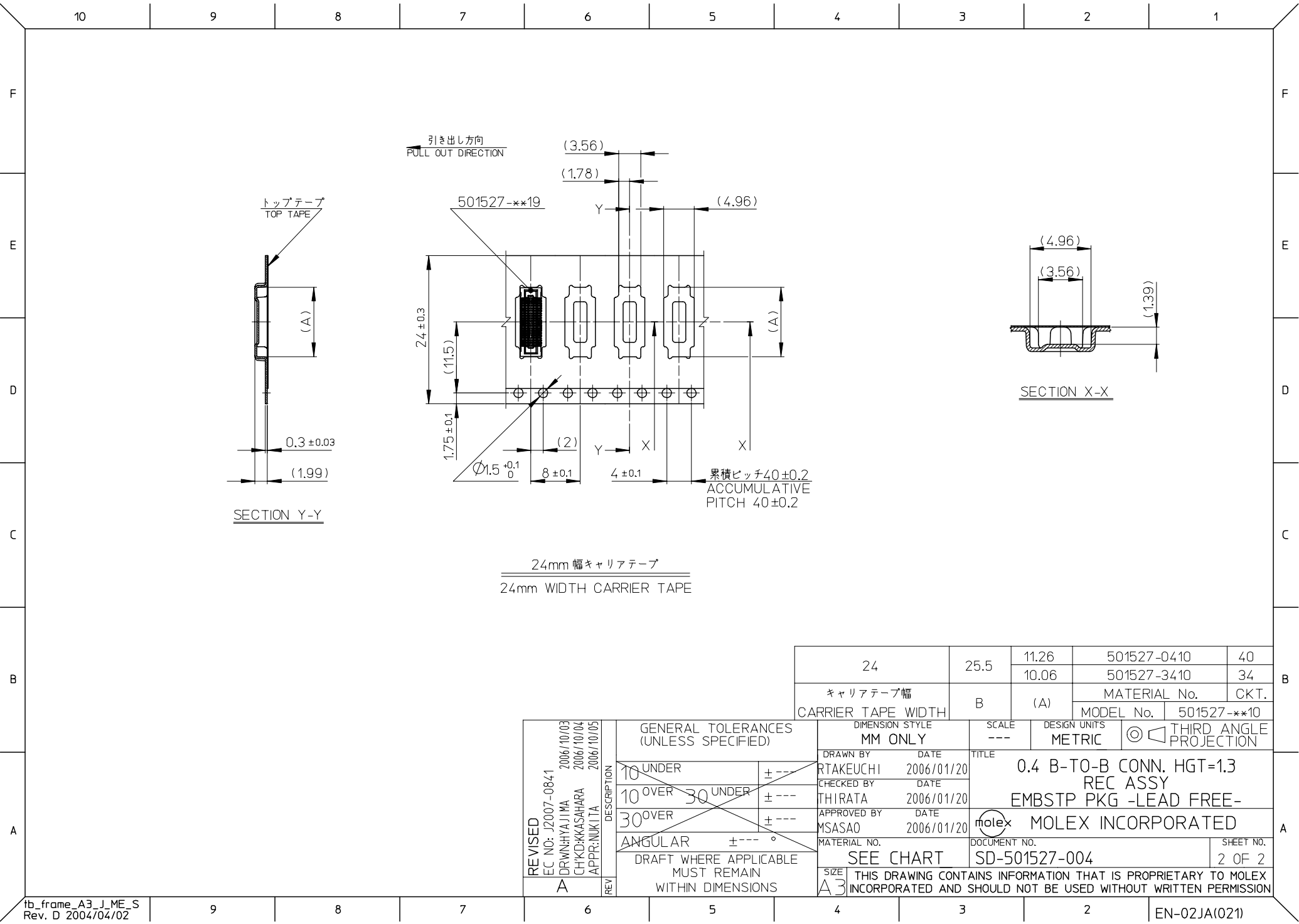


- D



- D

A



B

A

B

A